



## Material Content Data Sheet



<b>Sales Product Name</b>	TLE42994E			<b>Issued</b>	29. January 2016			
<b>MA#</b>	MA001355252							
<b>Package</b>	PG-SSOP-14-2			<b>Weight*</b>	83.48 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.995	3.59	3.59	35880	35880
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		103	
	non noble metal	zinc	7440-66-6	0.034	0.04		413	
	non noble metal	iron	7439-89-6	0.689	0.83		8254	
wire	non noble metal	copper	7440-50-8	27.978	33.51	34.39	335131	343901
	noble metal	gold	7440-57-5	0.152	0.18	0.18	1824	1824
	encapsulation	organic material	carbon black	1333-86-4	0.097	0.12		1159
plastics	plastics	epoxy resin	-	4.451	5.33		53312	
	inorganic material	silicondioxide	60676-86-0	43.830	52.50	57.95	525014	579485
leadfinish	non noble metal	tin	7440-31-5	0.976	1.17	1.17	11692	11692
plating	noble metal	silver	7440-22-4	0.768	0.92	0.92	9195	9195
glue	plastics	epoxy resin	-	0.376	0.45		4506	
	noble metal	silver	7440-22-4	1.128	1.35	1.80	13517	18023
*deviation	< 10%				Sum in total:	100.00		1000000

### Important Remarks:

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